Power MOSFET

28 V, 14 A, N-Channel, SO-8

Features

- Low RDS(on)
- High Power and Current Handling Capability
- Low Gate Charge

Applications

- DC/DC Converters
- Motor Drives
- Synchronous Rectifier POL
- Buck Low-Side

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	28	V
Gate-to-Source Voltage - Continuous	V _{GS}	±20	V
Drain Current Continuous @ $T_a = 25^{\circ}C$ (Note 1) Continuous @ $T_a = 25^{\circ}C$ (Note 2) Continuous @ $T_a = 25^{\circ}C$ (Note 3) Single Pulse (tp = 10 μ s)	I _D	14 12 9.0 40	A
Total Power Dissipation $T_A = 25^{\circ}C \text{ (Note 1)}$ $T_A = 25^{\circ}C \text{ (Note 2)}$ $T_A = 25^{\circ}C \text{ (Note 3)}$	P _D	2.5 1.66 0.93	W
Operating and Storage Temperature	T _J , T _{stg}	-55 to 150	°C
$\begin{array}{l} \mbox{Single Pulse Drain-to-Source Avalanche} \\ \mbox{Energy - Starting T}_{\mbox{J}} = 25^{\circ}\mbox{C} \\ \mbox{(V_{DD} = 30 V, V_{GS} = 10 V, I_{L} = 12.2 A,} \\ \mbox{L} = 1.0 \mbox{ mH, R_{G} = 25 Ω)} \end{array}$	E _{AS}	75	mJ
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	TL	260	°C

THERMAL RESISTANCE RATINGS

Rating	Symbol	Value	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Junction-to-Ambient (Note 2) Junction-to-Ambient (Note 3)	$R_{ hetaJA}$	50 75 135	°C/W

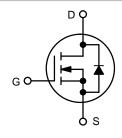
- 1. Surface–mounted on FR4 board using minimum recommended pad size (Cu area 0.412 in^2), t < 10 s.
- Surface-mounted on FR4 board using 1" pad size (Cu area 1.127 in²) steady state.
- Surface-mounted on FR4 board using minimum recommended pad size (Cu area 0.412 in²), steady state.



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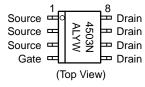
V _{(BR)DSS}	R _{DS(on)} TYP	I _D MAX (Note 1)	
28 V	7.0 m Ω @ 10 V	14 A	
20 V	8.8 mΩ @ 4.5 V	147	



MARKING DIAGRAM/ PIN ASSIGNMENT



SO-8 CASE 751 STYLE 12



4503N = Specific Device Code A = Assembly Location

L = Wafer Lot Y = Year W = Work Week

ORDERING INFORMATION

Device	Package	Shipping†	
NTMS4503NR2	SO-8	2500/Tape & Reel	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Characteristic	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		28	31	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /	-		-	22	-	mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	T _J = 25°C		_	-	1.0	μΑ
		$V_{GS} = 0 \text{ V}, V_{DS} = 24 \text{ V}$	T _J = 100°C	-	-	25	
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} =$	±20 V	-	-	±100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 2$	250 μΑ	1.0	_	2.0	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J	-		-	-5.0	-	mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D =	= 14 A	-	7.0	8.0	mΩ
		V _{GS} = 4.5 V, I _D =	= 10 A	-	8.8	9.8	
Forward Transconductance	9FS	V _{DS} = 10 V, I _D =	: 14 A	_	30	-	S
CHARGES, CAPACITANCES AND GATE RE	SISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1.0 MHz, V _{DS} = 16 A		-	2400	_	pF
Output Capacitance	C _{OSS}			-	1000	-	
Reverse Transfer Capacitance	C _{RSS}			-	375	-	
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 16 \text{ V}, I_D = 10 \text{ A}$		_	23	_	nC
Threshold Gate Charge	Q _{G(TH)}			_	2.0	_	
Gate-to-Source Charge	Q_{GS}			-	5.0	-	1
Gate-to-Drain Charge	Q_{GD}			-	12	-	
SWITCHING CHARACTERISTICS, $V_{GS} = V$	Note 5)						
Turn-On Delay Time	t _{d(ON)}			-	18.5	_	ns
Rise Time	tr	$V_{GS} = 4.5 \text{ V}, V_{DD} = 16$	V, I _D = 10 A,	-	70	-	
Turn-Off Delay Time	t _{d(OFF)}	$V_{GS} = 4.5 \text{ V}, V_{DD} = 16 \text{ V}, I_{D} = 10 \text{ A},$ $R_{G} = 2.0 \Omega$		_	21	_	
Fall Time	t _f			_	23	-	
DRAIN-SOURCE DIODE CHARACTERISTIC	S						
Forward Diode Voltage	V_{SD}	V 0VI 40A	$T_J = 25^{\circ}C$	-	0.82	1.2	V
		$V_{GS} = 0 \text{ V}, I_S = 10 \text{ A}$ $T_J = 125^{\circ}\text{C}$		_	0.65	-	
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, } d_{ISD}/d_t = 100 \text{ A/}\mu\text{s,}$ $I_S = 14 \text{ A}$		-	48	-	ns
Charge Time	T _a			-	23	-	
Discharge Time	T _b			_	25	-	
Reverse Recovery Charge	Q _{RR}			_	25	-	nC

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES

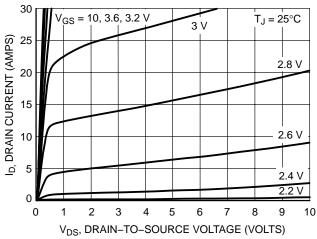


Figure 1. On–Region Characteristics

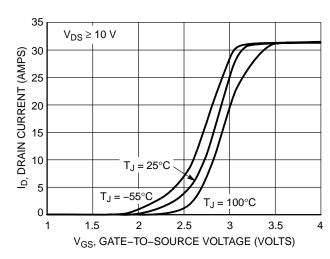


Figure 2. Transfer Characteristics

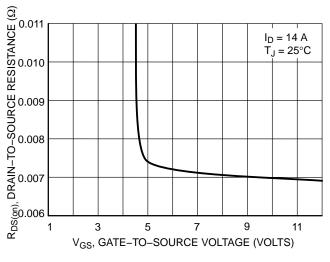


Figure 3. On–Resistance vs. Gate–to–Source Voltage

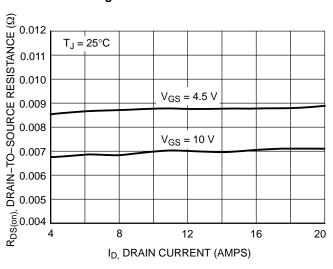


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

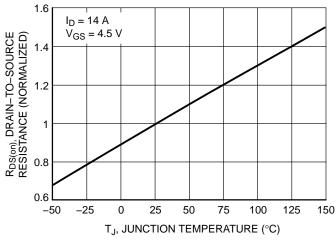


Figure 5. On–Resistance Variation with Temperature

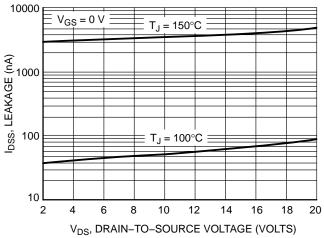
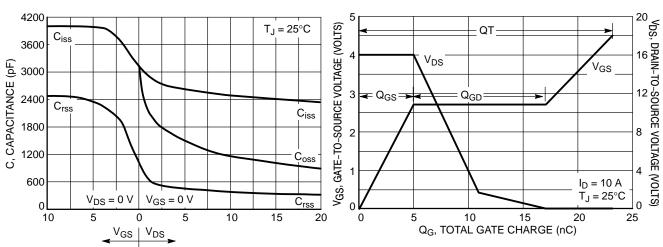


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL PERFORMANCE CURVES



GATE-TO-SOURCE OR DRAIN-TO-SOURCE VOLTAGE (VOLTS)

Figure 7. Capacitance Variation



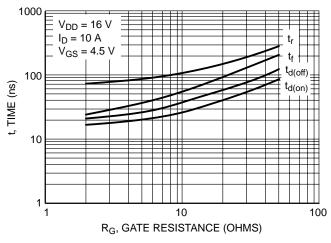


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

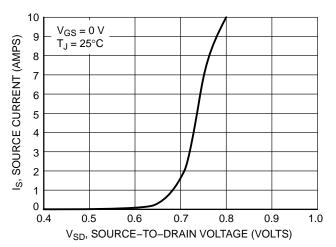
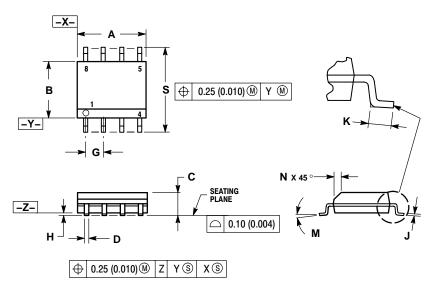


Figure 10. Diode Forward Voltage vs. Current

PACKAGE DIMENSIONS

SO-8 CASE 751-07 **ISSUE AA**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	4.80	5.00	0.189	0.197		
В	3.80	4.00	0.150	0.157		
С	1.35	1.75	0.053	0.069		
D	0.33	0.51	0.013	0.020		
G	1.27 BSC		0.05	50 BSC		
Н	0.10	0.25	0.004	0.010		
J	0.19	0.25	0.007	0.010		
K	0.40	1.27	0.016	0.050		
M	0 °	8 °	0 °	8 °		
N	0.25	0.50	0.010	0.020		
S	5.80	6.20	0.228	0.244		

- STYLE 12:
 PIN 1. SOURCE
 2. SOURCE
 3. SOURCE
 4. GATE

 - DRAIN
 - DRAIN DRAIN
 - 2. 3. 4. 5. 6. 7. 8. DRAIN

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